



Attorney Docket no: 0553-0193.01

A.UE.I  
Rec'd 12/05/05  
TL

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Takayama et al.

Serial No.: 10/672,521

Filed: September 26, 2003

For: Wiring Material, Semiconductor Device  
Provided With A Wiring Using The Wiring  
Material And Method of Manufacturing  
Thereof

Examiner: Ha T. Nguyen

Art Unit: 2812

Commissioner for Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450

I hereby certify that this correspondence is being  
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December 2, 2005  
(Date of Deposit)

Shannon Wallace

Name of applicant, assignee, or Registered Rep.

Shannon Wallace 12/2/05

Signature

Date

AMENDMENT D (AFTER FINAL)

In response to the Final Rejection of August 9, 2005 and the Advisory Action of November 22, 2005, a RCE and one month extension of time being submitted herewith, please amend the above-identified application as follows: